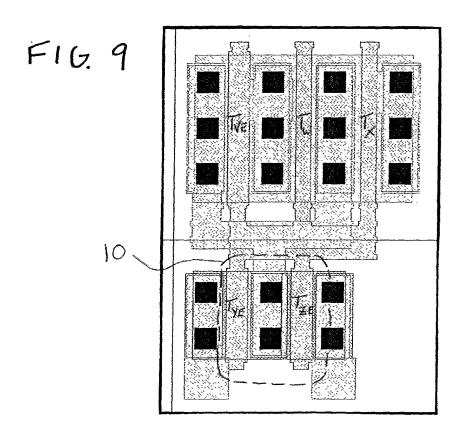
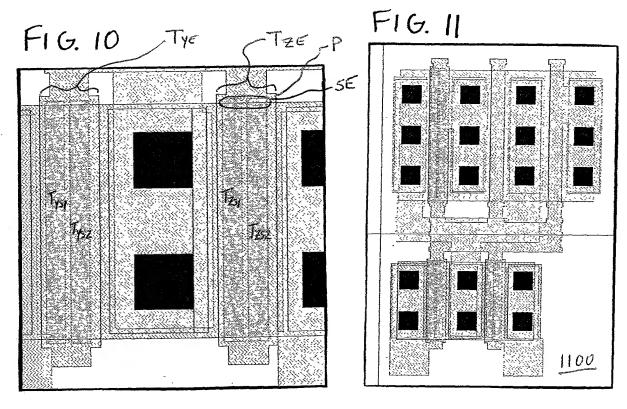


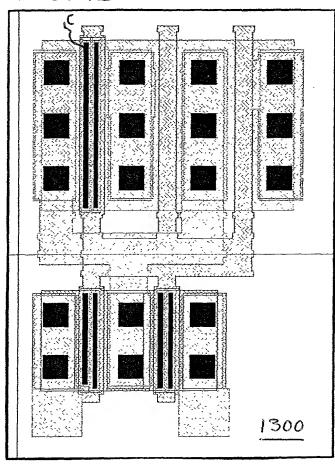
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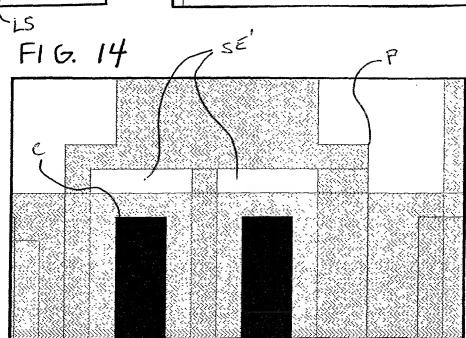




F16. 12

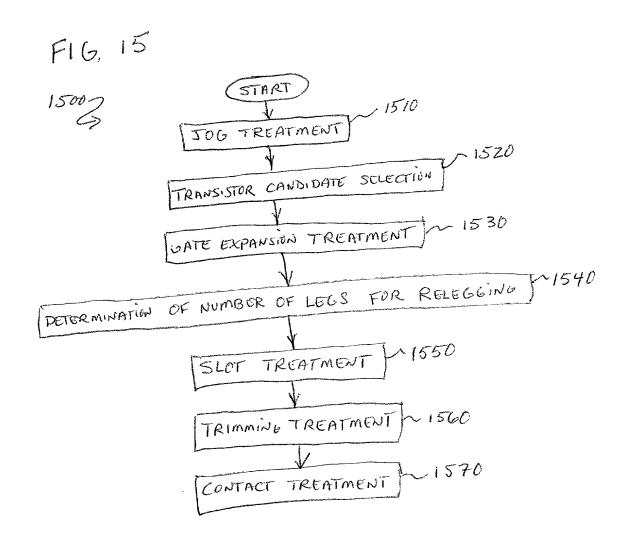
F16.13

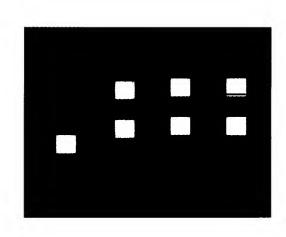




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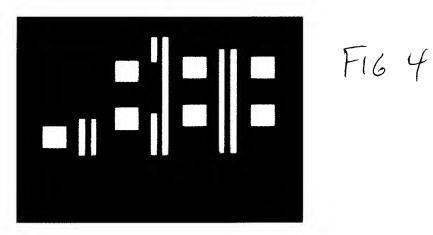




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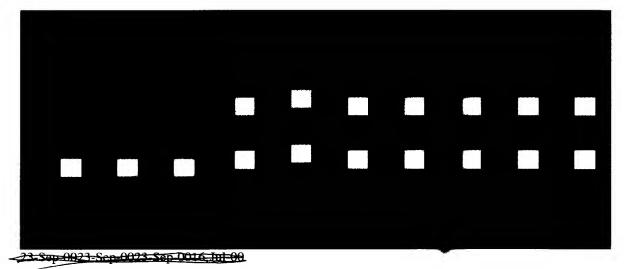
F16,3

(b) Prepare device for re-legging



(c) Re-legged device after compaction

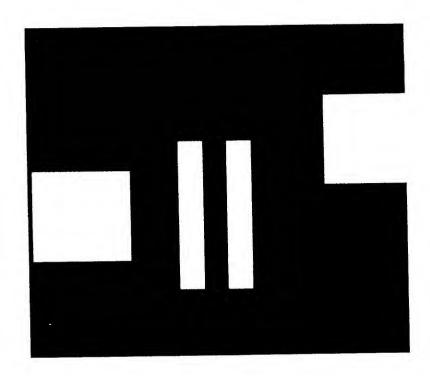
F16,6



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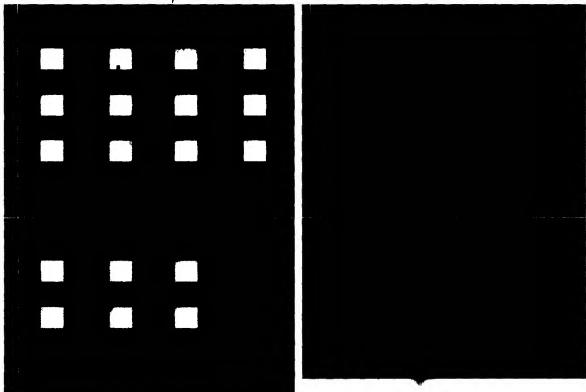
Re-legging layout flow

Re-legging is strongly connected to the performance (timing) of the layout and the target technology of prigration. This means that in a re-legging flow there are external directives which point to those legs in the layout for which re-legging needs to apply. The rest of discussion contains the essential steps and techniques of re-legging

Step1: Mark all transistors in layout

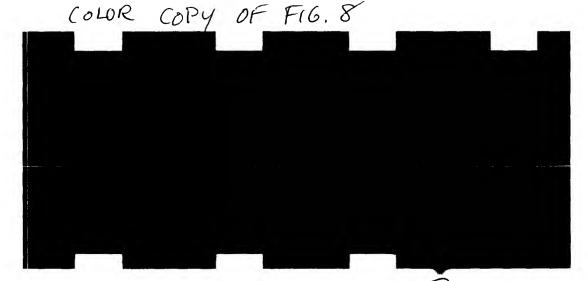
Intersecting poly-silicon and diffusion does this. The resulting shapes are the active gates of the transistors in layout. Following figures depict a cell for which the transistors are marked.

COLOR COPY OF FIG. 7



Step2/: Create poly-silicon and metall bumps

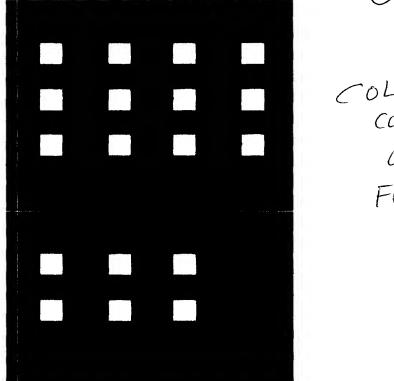
As shown in the figures, poly and motal straps connect P and N transistors. Since relegging requires significant exercising of the layout, the straight straps must be broken by jogs. Otherwise, the compactor that aims at stretching the layout will stack. The picture below depicts the launps put in between the P and N devices of the cell.



Step3: Expand devices to avail enough area for later slotting of gates

Let us aiming at re-legging three out of the five devices in the underlying cell. The external directives, which are out of the scope of this document, have directed to create re-legs in the left-most P device and the two N devices.

As we see later, the creation of new re-legs involves some "su gery" in the gate area of the ones exist in the layout. Since this area may be very small, some area expansion may



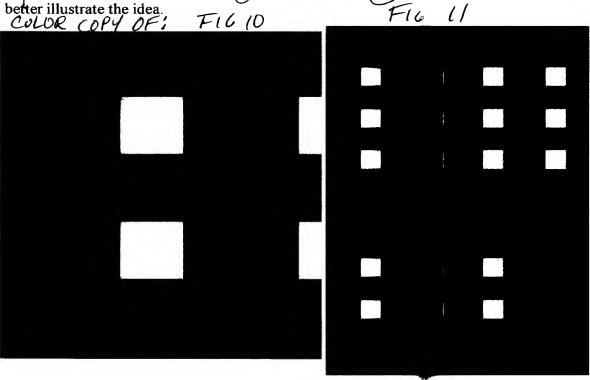
COLR CCY Fin. 9

be required. This expansion is shown in the next drawing. A stice the difference in the size of the gares aimed at re-legging and those that are not.

Step4: Device slotting preparation

In order to create new legs, slots are first be inserted into the layout at the tight places. These slots are put on top of the expanded gates described also e. In order to ease the reconnection of the newly created gates, re-legging maintains the evenness of the legs. Every leg, which is candidate for re-legging, defines therefore two slots, hat will later split it into three new legs.

Notice that in order to create the right topology of layout, these slots must extend beyond the area of diffusion. The drawing below depicts the slotting. A 1 N device is magnified to better illustrate the idea



Step5: Trimming poly under slots and contact preparations

Once slots are defined by the above step, once they are subtracted from the poly-silicon layer, an original normal leg is turned into three thin legs connected in parallel. Trimming poly-silicon leaves two uncovered diffusion between adjacent legs which is in the source node (and drain node) of two legs connected together.

Assume that the source node is the left uncovered. It then mus be connected to the right side of the original leg. In a similar way, the right uncovered diffusion, which is now the drain node, must be connected to the left side of the original leg. In order to ease this task, seeds of contacts covered by metal pads are implanted 11 the uncovered diffusion area.

Notice that all the above geometric manipulation, though creating right layout topology, entirely ignore any design rule. Thus, the resulting layout is illegal for manufacturing. It is the role of a compaction engine to return the layout into proper dimensions, obeying all technology rules. technology rules.

